

Report NO.: M000004000016

**1. Product information**

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJAC40SN03
Package Type :	PDFNWB5x6-8L

**2. MATERIAL ANALYSIS DATA SHEET**

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	4.6384%
Lead Frame	Copper	7440-50-8	97.52%	34.3246%
	Iron	7439-89-6	2.35%	
	P	7723-14-0	0.08%	
	Plating Ag	7440-22-4	0.05%	
	Lead	7439-92-1	83.4500%	
Epoxy	Tin	7440-31-5	4.5000%	3.6613%
	Silver	7440-22-4	2.1500%	
	Butanediol mixture	107-88-0	8.5000%	
	Modified castor oil	61788-85-0	1.4000%	
	Copper	7440-50-8	99.9976%	
Wire1	Others	/	0.0024%	2.3055%
	Copper	7440-50-8	97.95%	
	Palladium	7440/5/3	1.80%	
Wire2	Gold	7440-57-5	0.25%	52.6539%
	Silica	60676-86-0	86.4500%	
	Epoxy Resin	85954-11-6	6.5000%	
Mold Compound	Phenol Resin	26834-02-6	6.5000%	2.4164%
	Carbon black	1333-86-4	0.5500%	
	Tin	7440-31-5	99.99%	
	Other	/	0.01%	

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.